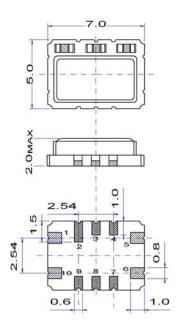
## **Specification**

Nominal Frequency Fo	20.0000 MHz	
Frequency stability :	±4.6 ppm	over all
Inclusive frequency stability vs. temperature, tolerance @+25°C, aging 15 years, supply & load variation		
Frequency stability vs. temperature	≤ ±0.28 ppm	over -40 ~ +85 °C
Short term aging	≤ ±0.004 ppm	over 24 hours
Holdover stability including supply change of ±5 % and aging	≤ ±0.37 ppm	over 24 hours
Frequency tolerance ex factory	≤ <b>±</b> 0.5 ppm	@+25°C
Supply voltage	+3.3 V	± 5 %
Current consumption	< 6 mA	
Output waveform	CMOS	
Output level	$V_{OH} \ge 0.9 \; Vdc$	$V_{OL} \le 0.1 \text{ Vdc}$
Output load	15 pF	
Start-up time	< 6 ms	
Tri-state function	pin #9 high or open pin #9 low	pin #6 → oscillation pin #6 → high impedance
Phase noise @ 20 MHz carrier frequency	< -90 dBc/Hz < -120 dBc/Hz < -135 dBc/Hz < -145 dBc/Hz	<ul><li>@ 10 Hz</li><li>@ 100 Hz</li><li>@ 1 kHz</li><li>@ 10 kHz</li></ul>
Operating temperature range	-40 ~ +85 °C	
Storage temperature range	-55 ~ +125 °C	
Packaging unit	tape & reel	1'000 pieces

# **Application**

Network synchronisation

### **Outline Dimensions & PIN Function & Solder Pattern**

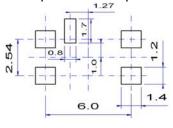


#### Pin function

# 1 not connected # 5 GND # 6 Output # 9 Tri-state # 10 Vdc

Do not contact #2, #3, #4, #7 & #8

### Example for solder pattern



Do not design any conductive path between the pattern Example for IR reflow soldering temperature

